



## AN 361

## Residual Copper Analysis on CMP Wafers

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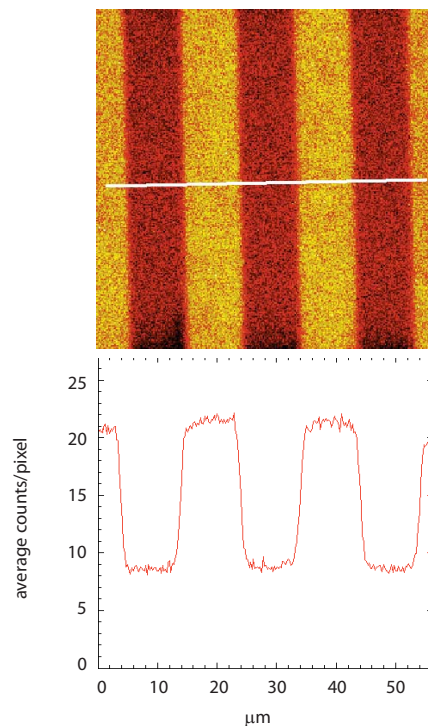
**Discussion**

The increasing use of copper in semiconductor devices requires changes in processing techniques and chemicals. Evaluating the effectiveness of these processes requires analytical approaches that can be used to determine the amount and distribution of residual copper present after removal steps such as CMP processing and post-CMP cleaning.

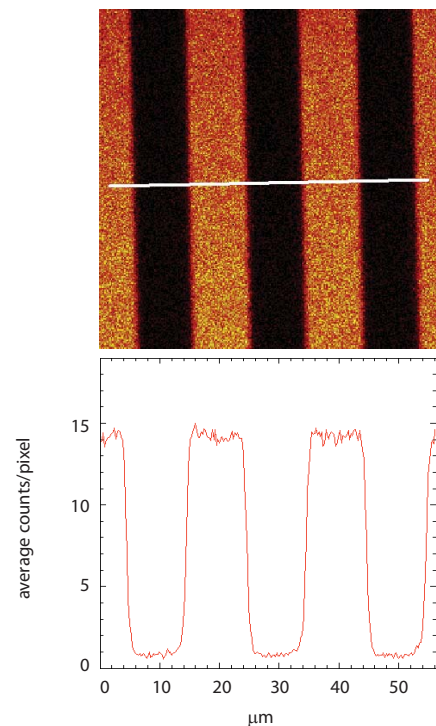
In work done in collaboration with OnTrak Systems, TOF-SIMS (Time-of-Flight Secondary Ion Mass Spectrometry) was used to measure Cu levels and distribution on the field oxides of two wafers processed by CMP and then treated using different cleaning mixtures. The wafers were patterned with test dies consisting of Cu line arrays of varying width and pitch. The table, which gives the calculated Cu concentrations in atoms/cm<sup>2</sup> at different points on the oxide of each wafer, indicates that cleaning process 1 (wafer 1) was less effective than process 2 (wafer 2) at removing Cu from the SiO<sub>2</sub>.

Figures 1 and 2 show the Cu distribution on an array of 10 μm Cu lines that are 10 μm apart. The Cu levels on the oxide between the metal lines were determined to be in the mid E14 at/cm<sup>2</sup> range for wafer 1 and in the low E13 at/cm<sup>2</sup> range for wafer 2.

	Wafer 1	Wafer 2
Away from Cu array	1.0E13	1.4E12
Near Cu array	1.4E13	2.4E12
Between Cu lines in array	5.7E14	1.1E13



**Figure 1. Cu ion image and line scan, wafer 1 (high Cu)**



**Figure 2. Cu ion image and line scan, wafer 2 (lower Cu)**

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**United States Locations**

Tempe, Arizona  
+1 480 239 0602 info.az@eaglabs.com  
+1 602 470 2655 fax

Sunnyvale, California  
810 Kifer Road  
+1 408 530 3500 info.ca@eaglabs.com  
+1 408 530 3501 fax

1135 E Arques Avenue  
+1 408 738 3033  
+1 408 530 3035 fax

785 Lucerne Drive  
+1 408 737 3892  
+1 408 737 3916 fax

Peabody, Massachusetts  
+1 978 278 9500 info.ma@eaglabs.com  
+1 978 278 9501 fax

Chanhassen, Minnesota  
+1 952 828 6411 info.mn@eaglabs.com  
+1 952 828 6449 fax

East Windsor, New Jersey  
+1 609 371 4800 info.nj@eaglabs.com  
+1 609 371 5666 fax

Syracuse, New York  
+1 315 431 9900 info.ny@eaglabs.com  
+1 315 431 9800 fax

Raleigh, North Carolina  
+1 919 829 7041 info.nc@eaglabs.com  
+1 919 829 5518 fax

Round Rock, Texas  
+1 512 671 9500 info.tx@eaglabs.com  
+1 512 671 9501 fax

**International Locations**

Shanghai, China  
+ 86 21 6879 6088 info.cn@eaglabs.com  
+ 86 21 6879 9086 fax

Tournefeuille, France  
+ 33 5 61 73 15 29 info.fr@eaglabs.com  
+ 33 5 61 73 15 67 fax

Frankfurt, Germany  
+ 49 (0) 693053213 info.de@eaglabs.com  
+ 49 (0) 69307941 fax

Tokyo, Japan  
+ 81 3 5396 0531 info.jp@eaglabs.com  
+ 81 3 5396 1930 fax

HsinChu, Taiwan  
+ 886 3 5632303 info.tw@eaglabs.com  
+ 886 3 5632306 fax

Uxbridge, United Kingdom  
+ 44 (0) 1895 811194 info.uk@eaglabs.com  
+ 44 (0) 1895 810350 fax